ModICE™ Modular Connector Enclosures

ModICE[™] is a complete line of connector enclosures that offers sealed packaging solutions for rugged electronic control modules. The Cinch 1.5mm SHS system is the base interconnect technology.

The ModICETM Advantage:

- 3 distinct enclosure sizes (ME, SE, LE)
- Multiple header configurations (18, 30, 48 and 60 I/O)
- Available Options:
 - ME Header with integrated RF Ports (SMA, RP-SMA)
 - Headers with integrated ferrite filtering
 - Blank headers for specific customer applications
 - Enclosures with integrated heat sink (SE and LE)
 - Vented enclosures (Breather vent)
- Simple module assembly with snap-in header/PCB



Product Specification

Operating Temperature: -40°C to +85°C

Current: 10 Amp @ 85°C Contact Resistance: $< 10 m\Omega$ Insulation Resistance: $> 1000 \text{ M}\Omega$

Sealing: IP67, IP69K

Temperature Life: 1000 Hrs @ 85°C Current Cycling: 500Hrs @ 10 Amp 500 cycles 45 min ON - 15 min OFF

Vibration: 10 to 2000 to 10 Hz with 15 g's peak level

Shock: 50 g's – 20 pulses

Salt Spray: 96 Hrs

Temperature Humidity Cycling: 320 Hrs 40 - 8 Hrs cycles -40°C to +85°C

Fluid Resistance: Resists to most fluids used in industrial applications

ME Enclosure

ModICE™ Enclosures



ME

	Enclosure	With Breather
Without Heat Sink	581 01 30 065	581 01 30 075

SE

	Enclosure	With Breather
Without Heat Sink	581 01 30 043	581 01 30 059
With One Heat Sink	581 01 30 042	581 01 30 058
With Two Heat Sinks	581 01 30 041	581 01 30 057

LE

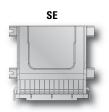
	Enclosure	With Breather
Without Heat Sink	581 01 60 033	581 01 60 039
With One Heat Sink	581 01 60 032	581 01 60 038
With Two Heat Sinks	581 01 60 031	581 01 60 037

SE & LE Spring Plate for Heat Sink Option

	Spring Plates
One Heat Sink	581 00 00 021
Two Heat Sinks	581 00 00 020 and 581 00 00 021

^{*} The heat sink option is only available on the SE and LE Enclosure.









For dimensions visit www.cinch.com